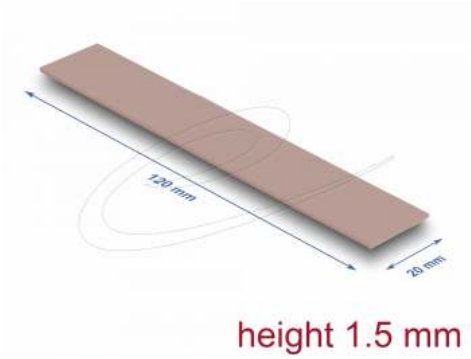
Delock Thermal Conductive Pad 120 x 20 x 1.5 mm for M.2 modules 3.0 W/mK - non-silicone

Description

This thermal conductive pad by Delock is suitable for heat dissipation, for example, on an M.2 module. The goal of the pad is to **improve performance and increase the service life** of the components. Typical areas of application for **silicone-free pads** can be found in industry and optoelectronics.



Non-silicone

Silicone-free pads do not release any oils that could contaminate or damage sensitive components. This makes them **ideal for sensitive electronics** such as sensors. Silicone-free pads can also be used in a wider temperature range without compromising their properties, which is particularly useful in industrial applications with **extreme temperatures**. In addition to the advantage of **longer durability**, they are also more **environmentally** friendly than conventional thermal pads.

Item no. 18482

EAN: 4043619184828

Country of origin: Taiwan, Republic of China

Package: Zip poly bag

Technical details

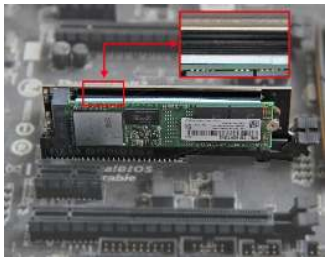
- Thermal pad for heat dissipation
- Thermal conductivity: 3.0 W/mK
- Operating temperature: -60 °C ~ 180 °C
- Colour: pink
- Dimensions (LxWxH): ca. 120 x 20 x 1.5 mm

Package content

- 1 x thermal conductive pad

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Images



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Physical characteristics

Thermal conductivity:	3.0 W/mK
Length:	120.0 mm
Width:	20 mm
Height:	1.5 mm

Manufacturer information

Street	Beeskowdamm 13/15
Postal code	14167
City	Berlin
Country	Deutschland
E-Mail	info@delock.de
Website	www.delock.de

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